

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yamauchi, M.

Serial No.: 09/733,036

Group Art Unit: 2828

Filed: December 11, 2000

Examiner: Leung, Q.

For: SEMICONDUCTOR LASER DIODE CHIP AND ITS POSITIONING AND  
MOUNTING METHODHonorable Assistant Commissioner of Patents  
Washington, D.C. 20231AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated January 17, 2001, please amend the above-  
identified application as follows:IN THE CLAIMS:

Please add the following new claims:

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Sub C27  
21. A semiconductor laser diode chip with an active layer mounted on a substrate,  
2 comprising:  
3 a first pair of marks formed in the vicinity of said active layer and straddling said  
4 active layer; and  
5 a second pair of marks straddling said active layer, said second pair of marks located  
6 at a further distance from said active layer than said first pair of marks,  
7 wherein said second pair of marks align with a pair of substrate side marks formed at  
8 a position opposed to said second pair of marks.

D1  
22. The semiconductor laser diode chip, as claimed in claim 21, wherein said first pair of  
marks comprises thin lines formed parallel to said active layer.

23. The semiconductor laser diode chip, as claimed in claim 22, wherein said first pair of  
marks are formed by a metallic film.